

MEG-00-012C

09/821,546

AF JFW

June 7, 2007

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/821,546 03/30/2001

J. Y. LEE

"A STRUCTURE AND MANUFACTURING  
METHOD OF CHIP SCALE PACKAGE"

Grp. Art Unit: 2811

D. W. OWENS

Please Do Not Enter  
Thank you.  
JW

# AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Final Office Action mailed April 20, 2007, please amend the above-identified application for patent and consider the remarks as follows:

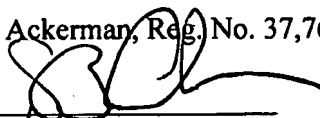
## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Jun. 20, 2007.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date

  
6/20/07